

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Pei-Haw Tsao</td><td>10/27/2006</td></tr><tr><td>Liang-Chen Lin</td><td>10/27/2006</td></tr><tr><td>Pao-Kang Niu</td><td>10/27/2006</td></tr><tr><td>I-Tai Liu</td><td>10/27/2006</td></tr><tr><td>Bill Kiang</td><td>10/27/2006</td></tr></tbody></table>	Name	Execution Date	Pei-Haw Tsao	10/27/2006	Liang-Chen Lin	10/27/2006	Pao-Kang Niu	10/27/2006	I-Tai Liu	10/27/2006	Bill Kiang	10/27/2006	
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Bill Kiang	10/27/2006												
RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.												
Street Address:	No. 8, Li-Hsin Road 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11557372</td></tr></tbody></table>	Property Type	Number	Application Number:	11557372									
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Application Number:	11557372												
CORRESPONDENCE DATA													
Fax Number:	(215)979-1020												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	(215) 979-1250												
Email:	lambriodes@duanemorris.com												
Correspondent Name:	Steven E. Koffs, Duane Morris LLP												
Address Line 1:	30 South 17th Street												
Address Line 4:	Philadelphia, PENNSYLVANIA 19103-4196												
ATTORNEY DOCKET NUMBER:	N1085-00453												
NAME OF SUBMITTER:	Steven E. Koffs												

CH \$40.00 11557372

PATENT

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Total Attachments: 3

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Serial No. 11/557,372

Filed: 11/07/2006

ATTORNEY DOCKET NO. 2006.0395/1085.453**ASSIGNMENT AND AGREEMENT**

For value received, we, **Pei-Haw Tsao, Liang-Chen Lin, Pao-Kang Niu, I-Tai Liu, and Bill Kiang**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **NOVEL BOND PAD DESIGN TO MINIMIZE DIELECTRIC CRACKING** described in an application for Letters Patent of the United States and all the rights and privileges in said application, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.


We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 10/27 '06

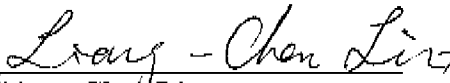

Pei-Haw Tsao

Residence:

7 F-1, No. 1 Nan-ho 2nd Street, Nan-Chu, Tai-chung, Taiwan, R.O.C.

Inventor No. 2

Dated: 10/27/2006



Liang-Chen Lin

Residence:

No. 13, Lane 37, Zhu-An 2nd Road, Baoshan Shiang, Hsinchu County, Taiwan, R.O.C.

Inventor No. 3

Dated: 10/27/2006


Pao-Kang Niu

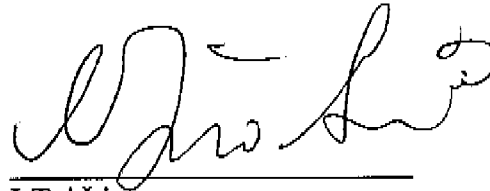
Residence:

No. 238-13, Wuling Road, Hsinchu City 300, Taiwan, R.O.C.

ATTORNEY DOCKET NO. 2006.0395/1085.453

Inventor No. 4

Dated: 10/27/06



I-Tai Liu

Residence:

2 F, No. 9, Lane 1, Dahsin Street Yung-Ho City, Taipei County, Taiwan, R.O.C.

Inventor No. 5

Dated: 10/29/06


Bill Kiang

Residence:

16 F.-1, No. 68, Dasyue Road, Hsinchu City 300, Taiwan, R.O.C.